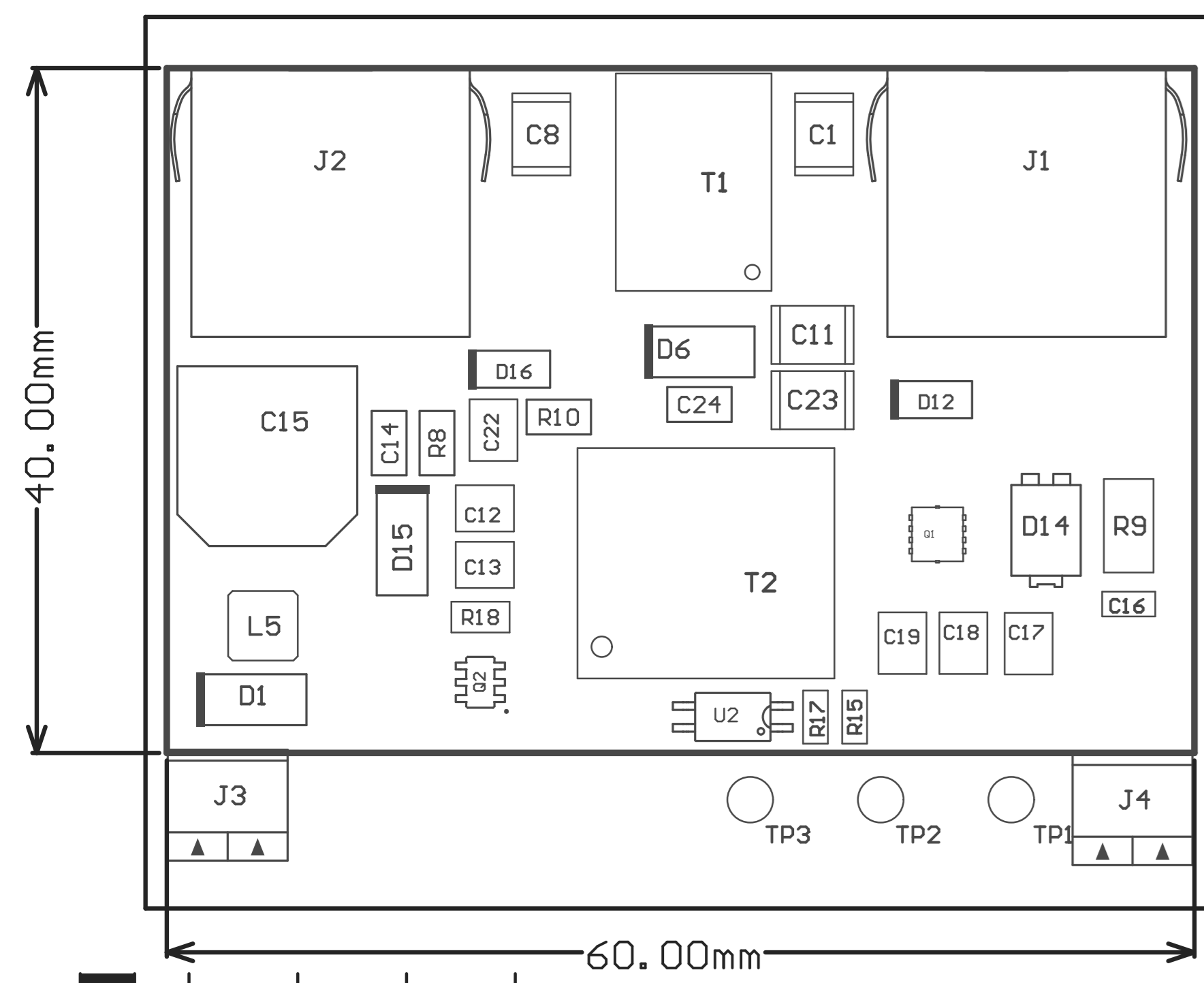


The reference design PMP30290 Rev_B has been built on PMP30290 Rev_A PCB



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

DESIGN INFORMATION	
MIN. TRACK WIDTH:	<u>8</u> MIL
MIN. CLEARANCE:	<u>0.2</u> mm
MIN. VIA PAD SIZE:	<u>24</u> MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL PER IPC-D-275 CLASS 2 LEVEL C	
REGISTRATION TOLERANCES: METAL +/- <u>5</u> MIL, HOLES +/- <u>3</u> MIL HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- <u>3</u> MIL	
MATERIAL:	
<input type="checkbox"/> FR-408 <input checked="" type="checkbox"/> FR-4 High Tg <input type="checkbox"/> OTHER _____	
THICKNESS:	<input checked="" type="checkbox"/> 62 MIL (1.6mm) +/-10% <input type="checkbox"/> OTHER _____
TOLERANCE:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2 <input type="checkbox"/> OTHER +/- _____
BOW & TWIST:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2 <input type="checkbox"/> OTHER +/- _____
DRILLING:	
REFERENCE:	<input checked="" type="checkbox"/> AS SHOWN <input checked="" type="checkbox"/> NC_DRILL FILES
PTH COPPER THICKNESS:	<input checked="" type="checkbox"/> 20-30 um <input type="checkbox"/> OTHER _____
BOARD FINISH:	
SILKSCREEN:	<input checked="" type="checkbox"/> TOP <input checked="" type="checkbox"/> BOTTOM
SILKSCREEN COLOR:	<input checked="" type="checkbox"/> WHITE <input type="checkbox"/> OTHER _____
SOLDER RESIST COLOR:	<input checked="" type="checkbox"/> GREEN <input type="checkbox"/> OTHER _____ <input checked="" type="checkbox"/> MATTE <input type="checkbox"/> SEMI-GLOSS
SURFACE FINISH:	<input checked="" type="checkbox"/> IMMERSION GOLD (ENIG) <input type="checkbox"/> ENEPIG <input type="checkbox"/> IMM. TIN/SILVER OR EQUIV <input type="checkbox"/> OTHER _____
ARRAY/PANEL:	<input type="checkbox"/> CUT AND TRIM PER M1 BOARD OUTLINE <input type="checkbox"/> N.C. ROUTE <input checked="" type="checkbox"/> V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:	
<input checked="" type="checkbox"/> ANSI IPC-A-600F CLASS -> <input type="checkbox"/> 1 <input checked="" type="checkbox"/> 2 <input type="checkbox"/> 3 <input checked="" type="checkbox"/> RoHS <input type="checkbox"/> OTHER PER ORDER	
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS. PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER	
ADDITIONAL REQUIREMENTS:	
MICROSECTION:	<input type="checkbox"/> YES
BARE BOARD ELEC. TEST:	<input type="checkbox"/> NONE <input checked="" type="checkbox"/> REQUIRED <input type="checkbox"/> PER ORDER



PROJECT TITLE:
High Efficiency PoE Flyback Converter

DESIGNED FOR:
Public Release

FILE NAME:
PMP30290 Rev_A PCB.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: PMP30290	REV: A	SUN REV: Not In VersionControl	Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.	ENGINEER: R. Scibilia	LAYOUT BY: R. Scibilia
	TID #: .TID				SCALE: 1.00	ALTIUM DESIGNER VERSION: 17.1.5.472
PLOT NAME = Top Layer Assembly Drawing	GENERATED : 11/7/2017 4:09:43 PM		TEXAS INSTRUMENTS			

DESIGN INFORMATION

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): ± 0.03 MIL
 REGISTRATION TOLERANCES: METAL ± 0.03 MIL HOLES ± 0.03 MIL
 PER IPC-D-275 CLASS 2 LEVEL C
 MINIMUM ANNUAL RING 0.025mm (SMIL) EXTERNAL
 MIN. VIA PAD SIZE: 0.24 MIL
 MIN. CLEARANCE: 0.2 mm
 MIN. TRACK WIDTH: 0.08 MIL

MATERIAL: FR-408 FR-4 High Tg OTHER

THICKNESS: 62 MIL (1.6mm) $\pm 10\%$ OTHER

TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2 OTHER ± 0.1

BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2 OTHER ± 0.1

DRILLING: REFERENCE: AS SHOWN NC DRILL FILES

PTH COPPER THICKNESS: 20-30 μ m OTHER

BOARD FINISH: SILKSCREEN: TOP BOTTOM

SILKSCREEN COLOR: WHITE OTHER

SOLDER RESIST COLOR: GREEN OTHER

SURFACE FINISH: IMMERSION GOLD (ENIG) ENPIG IMM. TIN/SILVER OR EQUIV OTHER

ARRAY PANEL: CUT AND TRIM PER M1 BOARD OUTLINE N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF: ANSI IPC-A-600F CLASS 2 1 3

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
 PCB MUST BEAR THE UL94-V0 REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS: MICROSECTION: YES NO

BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER

TEXAS INSTRUMENTS

PROJECT TITLE: High Efficiency PoE Flyback Converter

DESIGNED FOR: Public Release

FILE NAME: PMP30290_Rev_A_PCB.PcbDoc

LAYOUT BY: R. Scidilia

ENGINEER: R. Scidilia

SCALE: 1:00

DATE: 12.1.2017

completely revised your design implementation to confirm that the design is production ready. You should implement the design in your application. Texas Instruments (TI) and/or its licensors do not warrant that this design will meet the specifications for your application or fit for any particular purpose, or will operate in any manner. TI and/or its licensors do not warrant that this design will meet the specifications for your application or fit for any particular purpose, or will operate in any manner. TI and/or its licensors do not warrant that this design will meet the specifications for your application or fit for any particular purpose, or will operate in any manner.

PCB VIEWED FROM BOTTOM SIDE

TID #: .TID

PLOT NAME = Bottom Layer Assembly Drawing

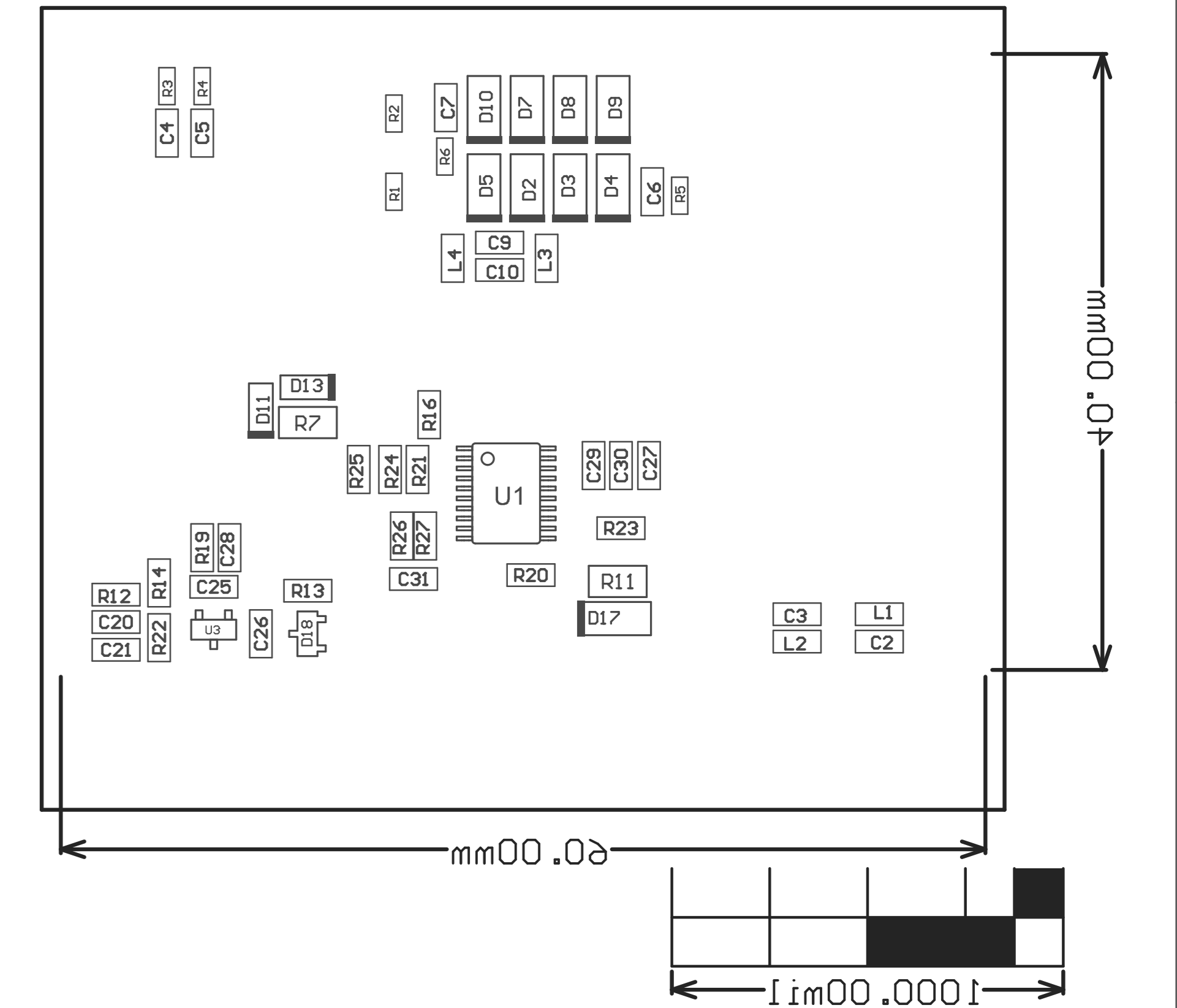
BOARD #: PMP30290

REV: A

SUN REV: Not In VersionControl

GENERATED : 11/7/2017 4:09:45 PM

TEXAS INSTRUMENTS



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 ASSEMBLY VARIANT: [No Variations]

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